

# MSP430FR5994 LaunchPad™ Development Kit



## eZ-FET on-board debug probe

Enables debugging/programming as well as communication back to the PC. The eZ-FET can also provide power to the target MCU.

Reset

40-pin BoosterPack  
plug-in module connector  
(J1 - J4)

MSP430FR5994 Microcontroller  
MSP1

User LEDs  
LED1 & LED2

Micro SD Card  
SD1

Super Capacitor  
C1

## EnergyTrace Technology

Real-time power consumption readings & state updates from the MSP430FR5994 MCU, including CPU and peripheral state are viewable through the EnergyTrace GUI

## Jumpers to isolate debug probe from target MCU (J101)

- Back-channel UART to PC (RXD, TXD)
- Spy-bi-wire debug (SBWTDIO/SBWTCK)
- Power (5V, 3V3, & GND)

User Buttons  
S1 & S2

Resources @  
[ti.com/launchpad](http://ti.com/launchpad)  
[ti.com/MSP-EXP430FR5994](http://ti.com/MSP-EXP430FR5994)

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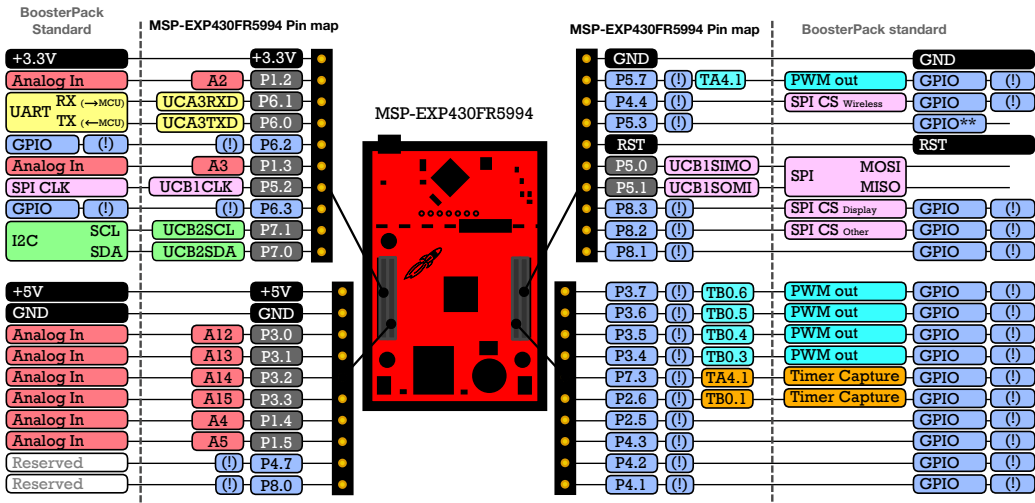
## Below are the pins exposed @ the MSP-EXP430FR5994 BoosterPack connector

Also shown are functions that map with the BoosterPack pinout standard. Refer to the MSP430FR5994 Datasheet for additional details

NOTE: Some LaunchPads & BoosterPacks do not 100% comply with the standard, so please check your specific LaunchPad to ensure pin compatibility

- (!) Denotes I/O pins that are interrupt-capable
- \*\* Some LaunchPads do not have a GPIO here

[ti.com/MSP-EXP430FR5994](http://ti.com/MSP-EXP430FR5994)



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